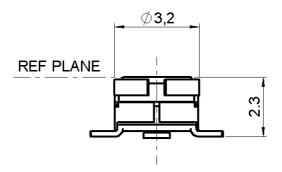
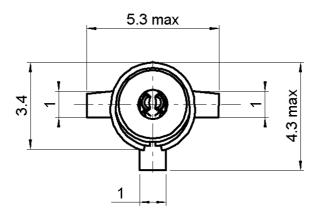
SMT TYPE - CC : GOLD 0.2 - REEL OF 100

R209.408.012

Series: MMS

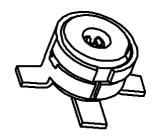






Scale 1/1

All dimensions are in mm.



| BODY PHOSPHOR BRONZE GOLD 0.2 | COMPONENTS | MATERIALS | PLATINGS (μm) | |
|--|--|---------------------------------------|----------------------|--|
| CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS | CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS | BERYLLIUM COPPER PHOSPHOR BRONZE PTFE | GOLD 0.2 GOLD 0.2 | |

Issue: 0421 A



SMT TYPE - CC: GOLD 0.2 - REEL OF 100

R209.408.012

Series: MMS

PACKAGING

| Standard | Unit | Other | |
|----------|------------|------------|--|
| 100 | 'W' option | Contact us | |

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω

VSWR * + 0.000 x F(GHz) Maxi Insertion loss * $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz)) dB mini
Voltage rating 50 Veff Maxi
Dielectric withstanding voltage 250 Veff mini

Dielectric withstanding voltage Insulation resistance 250 Veff mini 500 $M\Omega$ mini

ENVIRONMENTAL

Operating temperature -40/+125 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

*1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 50 Cycles mini

Weight **0.100** g

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SMT TYPE - CC: GOLD 0.2 - REEL OF 100

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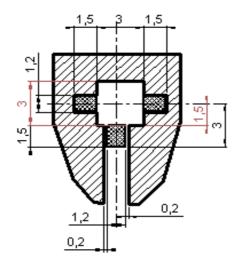
Series: MMS

MMS SERIES – INFORMATION

Coplanar line: Ground and signal are on the same side. Thicknass of PCB: 1mm

The material of PCB is glass-epoxy composite. (Er = 4.8)

The sold er resist should be printed except for the land pattern on the PCB.



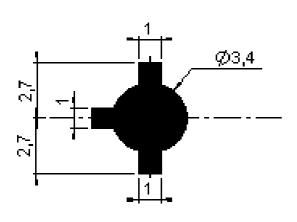


Pattern

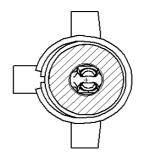


Land for solder paste

SHADOW OF MMS RECEPTACLE FOR VIDEO CAMERA



ASPIRATION AREA





ASPIRATION AREA

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SMT TYPE - CC: GOLD 0.2 - REEL OF 100

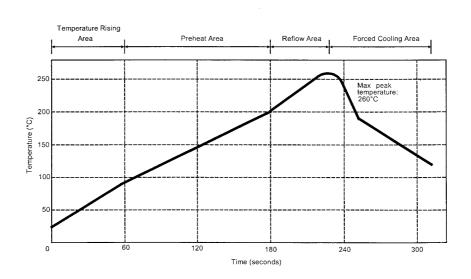
R209.408.012

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SOLDER PROCEDURE

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
- 3. Soldering by infra-red reflow.
- Cleaning of printed circuit boards.
- Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



| Parameter | Value | Unit |
|----------------------------------|----------|--------|
| Temperature rising Area | 1 - 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to -4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |

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In the effort to improve our products, we reserve the right to make changes judged to be

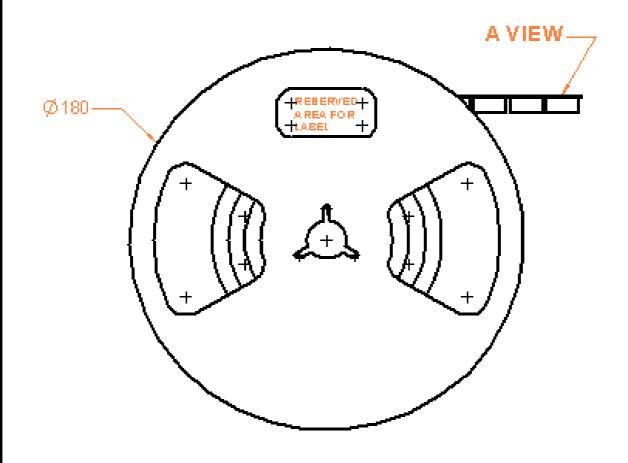
necessary.

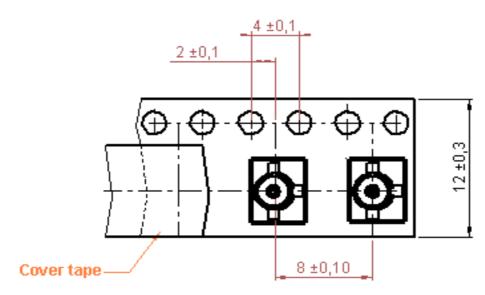


SMT TYPE - CC: GOLD 0.2 - REEL OF 100

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Series : MMS





A VIEW (scale: 4)

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